

## T495B107M006ATE700

T495, Tantalum, MnO2 Tantalum, Commercial Grade, 100 uF, 20%, 6.3 VDC, SMD, MnO2, Molded, Low ESR, 700 mOhms, 3528, 2.1 mm, 0.8 mm

CATHODE (-) END VIEW

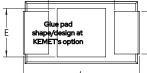


ANODE (+) END VIEW

Х

B - S G -S BOTTOM VIEW Α-

SIDE VIEW



		AEC-Q200
	Glue pad shape/design at F KEMET's option	Typical Component We
		Shelf Life
	L	MSL
Click here for	the 3D model.	
Dimensions		Specifications
L	3.5mm +/-0.2mm	Capacitance
W 2.8mm +/-0.2mm		Tolerance
H 1.9mm +/-0.2mm		Voltage DC
T 0.13mm REF		Temperature Range
S 0.8mm +0.1/-0.3mm		Rated Temperature
F 2.2mm +/-0.1mm		Dissipation Factor
A 1.9mm MIN		Failure Rate
B 0.4mm +/-0.15mm		ESR
E 2.2mm REF		<b>Ripple Current</b>
G 1.8mm REF		
P 0.5mm REF		Leakage Current
R 1mm REF		

General Information	
Series	T495
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, Low ESR
Features	Low ESR
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	107.45 mg
Shelf Life	156 Weeks
MSL	1

Specifications	
Capacitance	100 uF
Tolerance	20%
Voltage DC	6.3 VDC (85C), 4.22 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	15% 120Hz 25C
Failure Rate	N/A
ESR	700 mOhms (100kHz 25C)
Ripple Current	348 mA (rms, 100kHz 25C), 313.2 mA (rms, 85C), 139.2 mA (rms, 125C)
Leakage Current	6.3 uA (5min 25°C)

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	2000

0.1mm +/-0.1mm REF

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

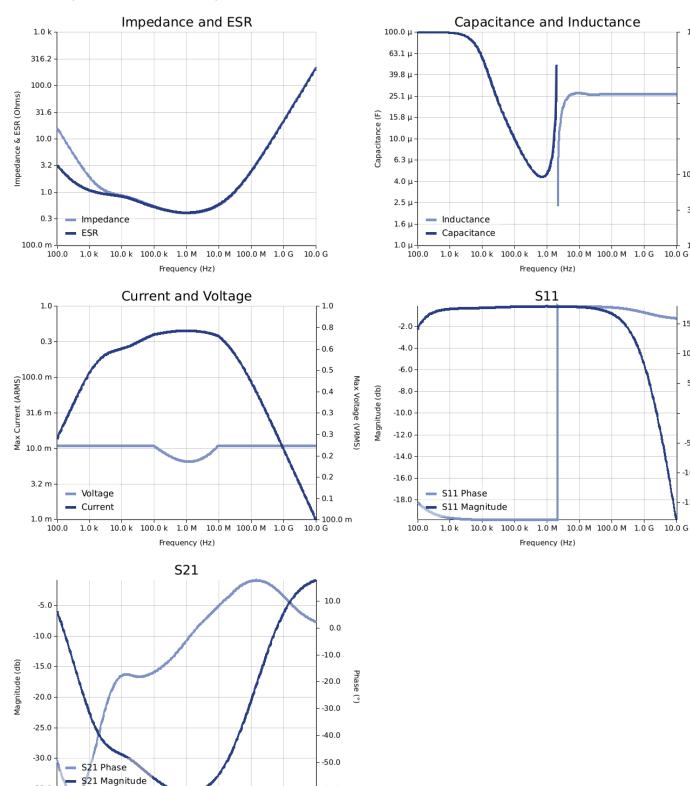


## T495B107M006ATE700

T495, Tantalum, MnO2 Tantalum, Commercial Grade, 100 uF, 20%, 6.3 VDC, SMD, MnO2, Molded, Low ESR, 700 mOhms, 3528, 2.1 mm, 0.8 mm

## Simulations

For the complete simulation environment please visit K-SIM.



-60.0

10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G 10.0 G

Frequency (Hz)

100.0

1.0 k

-35.0

10.0 n

3.2 n

1.0 n

0.3 n

100.0 p

31.6 p

10.0 p

150.0

100.0

50.0

0.0

-50.0

-100.0

-150.0

10.0 G

Phase (°)

Inductan

Ē



T495, Tantalum, MnO2 Tantalum, Commercial Grade, 100 uF, 20%, 6.3 VDC, SMD, MnO2, Molded, Low ESR, 700 mOhms, 3528, 2.1 mm, 0.8 mm

## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance. The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.
  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.